

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN 20190625000 Qualify New Assembly Material for Automotive PDIP devices Final Change Notification

Date: July 01, 2019 **To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

If samples or additional data are required, requests must be received within 30 days of acknowledgement as samples are not built ahead of the change. You may contact the PCN Manager or your local Field Sales Representative to acknowledge this PCN and request samples or additional data.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

20190625000 Final Change Notification Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SE555P	null
TPIC6259N	null
TPIC6273N	null
TPIC6595N	null
TPIC6A595NE	null
TPIC6B259N	null
TPIC6B595N	null
TPIC6C595N	null
TPIC6C596N	null
TPIC6B273N	null

Technical details of this Product Change follow on the next page(s).

PCN Number:		20190625000						PCN Date: July 1, 2019				
Qualify New Assembly Material for Automotive PDIP devices												
Customer Contact	:	PCN Man	<u>ager</u>				Dept:		Quality Services			
Proposed 1 st Ship Date: Jan. 1, 20					Estimate Availa			e		provided at		
Change Type:			Availability: sample request									
Assembly Site				Design				Waf	er Bur	np Site		
Assembly Proce	SS			Data Sheet					Wafer Bump Material			
Assembly Mater					ber change				Wafer Bump Process			
Mechanical Spec			44	Test Site			<u>Ц</u>	_	Wafer Fab Site			
Packing/Shippin	<u>ıg/Labeli</u>	ng		Test Proc	ess		<u> </u>		Vafer Fab Materials			
_				PCN Det	nile.			Wafer Fab Process				
Description of Cha	nge			PCN Del	.alis							
Texas Instruments is		to anno	unce	the qualific	cation of ne	ew as	sem	ıblv n	nateria	l set for devices		
listed in "Product aff												
part changes as follo		, -					- '		,	, , ,		
										1		
Materia	al	Current			N	New Material						
	Leadframe			Non-Roughened			Single Sided Roughened					
Wire	Au				No change							
Mount compo		4042500			4147858							
Mold compou	ınd		4042	2503		421	11880					
Reason for Change	e:											
To align with universal BOM (UBOM) material strategy.												
Anticipated impac	t on Fit,	Form, I	unct	tion, Quali	ty or Relia	abilit	y (r	ositi	ive / ı	negative):		
None.												
Changes to produc	ct identi	fication	resu	ılting fron	this PCN	:						
None.												
Product Affected:												
SE555P T	TPIC6273N		TPIC	5B273N								
SN103442N T	N103442N TPIC6595N		TPIC6B595N									
SN104599N T	TPIC6596N		TPIC	C6B596N								
TLC2274MN T	TPIC6A259NE		TPIC	6C595N								
TLC339MN T			TPIC	6C596N								
				2003AN								
	+			2004AN								
	11160523314				1							

Automotive New Product Qualification Summary (As per AEC-Q100 and JEDEC Guidelines)

Approved 26-Mar-2019

Product Attributes Attributes	Qual Device: SE555P	Qual Device: SN104571P	Qual Device: <u>TPIC6A596NE</u>
Automotive Grade Level	Grade 1	Grade 1	Grade 1
Operating Temp Range	-55 to +125 C	-40 to +125 C	-40 to +125 C
Product Function	Signal Chain	Power Management	Power Management
Wafer Fab Supplier	SFAB	SFAB	DFAB
Die Revision	В	E	A
Assembly Site	FMX	FMX	MLA
Package Type	PDIP	PDIP	PDIP
Package Designator	P	P	NE
Ball/Lead Count	8	8	20

⁻ Qual Devices SE555P, SN104571P and TPIC6A596NE are qualified at NC-P

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Ту	/pe	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: SE555P	Qual Device: SN104571P	Qual Device: TPIC6A596NE
	T	est G	roup A – A	ccelera						
НА	AST	A2	JEDEC JESD22- A110	3	77	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
A	ıC	A3	JEDEC JESD22- A102	3	77	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0
T	°C	A4	JEDEC JESD22- A104 and Appendix	3	77	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
	C- BP	A4	MIL- STD883 Method 2011	1	60	Post TC Bond Pull	Wires	3/90/0	3/90/0	3/90/0
РТ	ГС	A5	JEDEC JESD22- A105	1	45	Power Temperature Cycle	1000 Cycles	N/A	N/A	N/A
НТ	TSL	A6	JEDEC JESD22- A103	1	45	High Temp Storage Bake 175C	500 Hours	3/135/0	3/135/0	3/135/0
	T	est G	roup B – Ac	ccelera	ted Lifetiı	me Simulation Test	ts			
НТ	COL	B1	JEDEC JESD22- A108	3	77	Life Test, 125C	1000 Hours	-	-	3/231/0
ED	OR	В3	AEC Q100- 005	3	77	NVM Endurance, Data Retention, and Operational Life	-	N/A	N/A	N/A
		Test	Group C -	Packag	ge Asseml	oly Integrity Tests				

Туре	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: <u>SE555P</u>	Qual Device: <u>SN104571P</u>	Qual Device: TPIC6A596NE
WBS	C1	AEC Q100- 001	1	30	Wire Bond Shear (Cpk>1.67)	Wires	3/90/0	3/90/0	3/90/0
WBP	C2	MIL- STD883 Method 2011	1	30	Wire Bond Pull (Cpk>1.67)	Wires	3/90/0	3/90/0	3/90/0
SD	C3	JEDEC JESD22- B102	1	15	Solderability	Pb Free Solder	3/45/0	3/45/0	3/45/0
SD	C3	JEDEC JESD22- B102	1	15	Solderability	Pb Solder	3/45/0	3/45/0	3/45/0
PD	C4	JEDEC JESD22- B100 and B108	3	10	Physical Dimensions (Cpk>1.67)	-	3/30/0	3/30/0	3/30/0
LI	C6	JEDEC JESD22- B105	1	50	Lead Integrity	Leads	1/50/0	1/50/0	1/50/0
	Tes	t Group D –	Die Fa	abrication	Reliability Tests				
EM	D1	JESD61	-	-	Electromigration	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependant Dielectric Breakdown	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
НСІ	D3	JESD60 & 28	-	-	Hot Injection Carrier	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
NBTI	D4	-	-	-	Negative Bias Temperature Instability	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
	T	<u> 'est Group</u> I	E – Elec	ctrical Ve	rification Tests				
ED	E5	AEC Q100- 009	3	30	Auto Electrical Distributions	Cpk>1.67 Room, hot, and cold test	Pass	-	Pass

Ambient Operating Temperature by Automotive Grade Level: Grade 0 (or E): -40°C to +150°C

Grade 0 (or E): -40° C to $+150^{\circ}$ C Grade 1 (or Q): -40° C to $+125^{\circ}$ C Grade 2 (or T): -40° C to $+105^{\circ}$ C Grade 3 (or I): -40° C to $+85^{\circ}$ C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold: HTOL, ED

Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room: AC/uHAST

Green/Pb-free Status:

Qualified Pb-Free(Throuh-hole) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN www admin_team@list.ti.com